

SEMICONDUCTOR DEVICE WITH ANCHOR TYPE SEAL RING

ABSTRACT OF THE DISCLOSURE

A semiconductor package seal ring including a plurality of insulating layers, a plurality of conductive runners each embedded in one of the insulating layers, and a plurality of conductive posts each contacting one of the conductive runners and extending through at least one of the insulating layers and at least partially through an opening in another one of the conductive runners.

(FIG. 1)